mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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July 2016

Chip beads

For general signal line

MMZ series (for automobiles)

MMZ2012 Type

MMZ2012

2012[0805 inch]*

* Dimensions code JIS[EIA]

Reminders for using these products

Before using these products, be sure to request the delivery specifications.

Safety reminders

Please pay sufficient attention to the warnings for safe designing when using this products.

▲ Re	⚠ Reminders				
The storage period is less than 12 months. Be sure to follow the storage conditions (temperature:5 to 40°C, humidity:10 to 75% RH or less).					
If the storage period elapses, the soldering of the terminal electrodes may deteriorate.					
\bigcirc Do not use or store in locations where there are conditions such	n as gas corrosion (salt, acid, alkali, etc.).				
 Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperators does not exceed 150°C. 	ature difference between the solder temperature and chip temperature				
 Soldering corrections after mounting should be within the range If overheated, a short circuit, performance deterioration, or lifes 					
○ When embedding a printed circuit board where a chip is mount the overall distortion of the printed circuit board and partial disto	ted to a set, be sure that residual stress is not given to the chip due to prtion such as at screw tightening portions.				
 Self heating (temperature increase) occurs when the power is design. 	s turned ON, so the tolerance should be sufficient for the set thermal				
 Carefully lay out the coil for the circuit board design of the non-r A malfunction may occur due to magnetic interference. 	nagnetic shield type.				
\bigcirc Use a wrist band to discharge static electricity in your body thro	ugh the grounding wire.				
\bigcirc Do not expose the products to magnets or magnetic fields.					
\bigcirc Do not use for a purpose outside of the contents regulated in th	e delivery specifications.				
ment, home appliances, amusement equipment, computer eq ment, industrial robots) under a normal operation and use cond The products are not designed or warranted to meet the require ity require a more stringent level of safety or reliability, or whose person or property.	neral electronic equipment (AV equipment, telecommunications equip- uipment, personal equipment, office equipment, measurement equip- ition. ments of the applications listed below, whose performance and/or qual- e failure, malfunction or trouble could cause serious damage to society, or if you have special requirements exceeding the range or conditions				
 (1) Aerospace/aviation equipment (2) Transportation equipment (electric trains, ships, etc.) (3) Medical equipment (4) Power-generation control equipment (5) Atomic energy-related equipment (6) Seabed equipment (7) Transportation control equipment 	 (8) Public information-processing equipment (9) Military equipment (10) Electric heating apparatus, burning equipment (11) Disaster prevention/crime prevention equipment (12) Safety equipment (13) Other applications that are not considered general-purpose applications 				
When designing your equipment even for general-purpose applica tection circuit/device or providing backup circuits in your equipmen	tions, you are kindly requested to take into consideration securing pro- t.				

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EMC Components

Chip beads

For general signal line

Product compatible with RoHS directive Halogen-free Compatible with lead-free solders AEC-Q200

Overview of MMZ2012 type

FEATURES

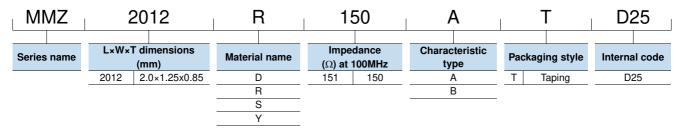
O Noise reduction solution for general signal line.

○ Various frequency characteristics with 4 materials of different features for countermeasures against everything from general signals to high-speed signals.

APPLICATION

Various ECUs, powertrains, body controls, and car multimedia (telematics).

PART NUMBER CONSTRUCTION



OPERATING TEMPERATURE RANGE, PACKAGE QUANTITY, PRODUCT WEIGHT

	Temperatu	ure ranges	Package quantity	Individual weight	
Туре	Operating temperature	Storage temperature*			
	(°C)	(°C)	(pieces/reel)	(mg)	
MMZ2012	-55 to +125	-55 to +125	4,000	8	

* The storage temperature range is for after the circuit board is mounted.

O RoHS Directive Compliant Product: See the following for more details.https://product.tdk.com/info/en/environment/rohs/index.html

O Halogen-free: indicates that CI content is less than 900ppm, Br content is less than 900ppm, and that the total CI and Br content is less than 1500ppm.

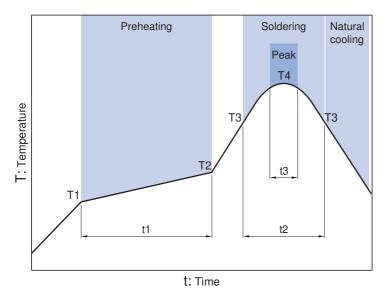
Please be sure to request delivery specifications that provide further details on the features and specifications of the products for proper and safe use. Please note that the contents may change without any prior notice due to reasons such as upgrading.

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(4/11)

MMZ2012 type

RECOMMENDED REFLOW PROFILE

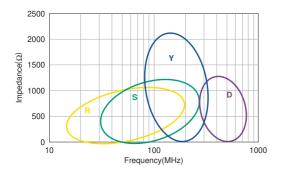


Preheating		Soldering	Soldering		Peak	
Temp.		Time	Temp.	Time	Temp.	Time
T1	T2	t1	Т3	t2	T4	t3
150°C	180°C	60 to 120s	230°C	30 to 60s	250 to 260°C	10s

MATERIAL CHARACTERISTIC

- R material: For wide frequency applications calling for broad impedance characteristics. For digital signal line applications calling requiring good waveform integrity. Impedance values selected for effectiveness at 10 to 200MHz.
- S material: Standard type that features impedance characteristics similar to those of a typical ferrite core. For signal line applications in which the blocking region is near 100MHz. Impedance values selected for effectiveness at 40 to 300MHz.
- Y material: High frequency range type intended for the 100MHz region and above. For signal line applications in which the signal frequency is far from the cutoff frequency. Impedance values selected for effectiveness at 80 to 400MHz.
- D material: For applications calling for low insertion loss at low frequencies and sharply increasing impedance at high frequencies. Designed for high impedance at high frequencies (300MHz to 1GHz) for signal line applications.

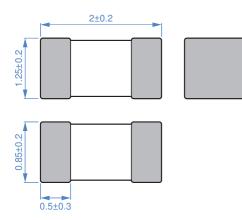
TYPICAL MATERIAL IMPEDANCE CHARACTERISTICS



Please be sure to request delivery specifications that provide further details on the features and specifications of the products for proper and safe use. Please note that the contents may change without any prior notice due to reasons such as upgrading.

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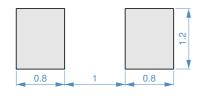
SHAPE & DIMENSIONS



Dimensions in mm



RECOMMENDED LAND PATTERN



Dimensions in mm

A Please be sure to request delivery specifications that provide further details on the features and specifications of the products for proper and safe use. Please note that the contents may change without any prior notice due to reasons such as upgrading.

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ELECTRICAL CHARACTERISTICS

CHARACTERISTICS SPECIFICATION TABLE

Impedance		DC resistance	Rated current	Part No.
[100MHz]				
	Tolerance	(Ω) max.	(mA)max.	
15	±25%	0.05	1500	MMZ2012R150ATD25
30	±25%	0.05	1500	MMZ2012R300ATD25
60	±25%	0.10	1000	MMZ2012R600ATD25
120	±25%	0.12	800	MMZ2012R121ATD25
300	±25%	0.15	600	MMZ2012R301ATD25
600	±25%	0.20	500	MMZ2012R601ATD25
1000	±25%	0.30	500	MMZ2012R102ATD25
40	±25%	0.10	1000	MMZ2012S400ATD25
80	±25%	0.10	800	MMZ2012S800ATD25
120	±25%	0.15	800	MMZ2012S121ATD25
180	±25%	0.15	600	MMZ2012S181ATD25
300	±25%	0.20	600	MMZ2012S301ATD25
600	±25%	0.30	500	MMZ2012S601ATD25
1000	±25%	0.35	500	MMZ2012S102ATD25
15	±25%	0.05	1500	MMZ2012Y150BTD25
30	±25%	0.05	1500	MMZ2012Y300BTD25
60	±25%	0.10	1000	MMZ2012Y600BTD25
120	±25%	0.12	800	MMZ2012Y121BTD25
300	±25%	0.15	600	MMZ2012Y301BTD25
600	±25%	0.20	500	MMZ2012Y601BTD25
1000	±25%	0.30	500	MMZ2012Y102BTD25
1500	±25%	0.40	500	MMZ2012Y152BTD25
2000	±25%	0.50	400	MMZ2012Y202BTD25
80	±25%	0.30	500	MMZ2012D800BTD25
120	±25%	0.30	500	MMZ2012D121BTD25
300	±25%	0.50	400	MMZ2012D301BTD25

$\bigcirc {\rm Measurement\ equipment}$

Measurement item	Product No.	Manufacturer
Impedance	E4991A+16192A	Keysight Technologies
DC resistance	Type-7556	Yokogawa

* Equivalent measurement equipment may be used.

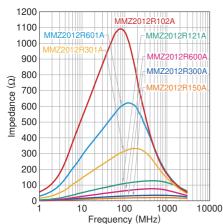
公TDK

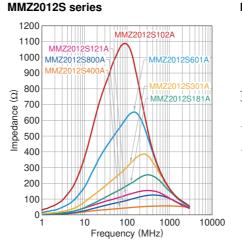
MMZ2012 type

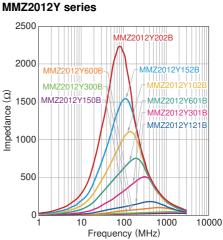
ELECTRICAL CHARACTERISTICS

□ Z VS. FREQUENCY CHARACTERISTICS (BY SERIES)

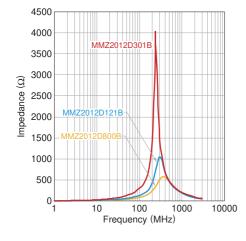
MMZ2012R series







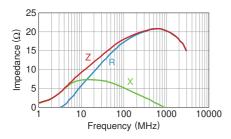
MMZ2012D series

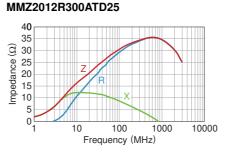


ELECTRICAL CHARACTERISTICS

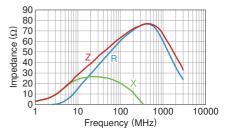
Z, X, R VS. FREQUENCY CHARACTERISTICS

MMZ2012R150ATD25

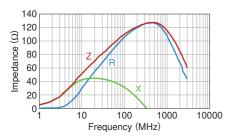




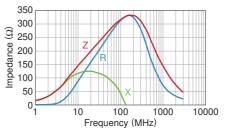
MMZ2012R600ATD25



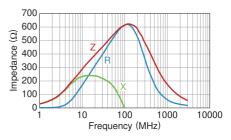
MMZ2012R121ATD25



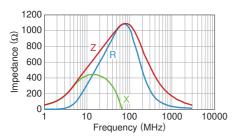
MMZ2012R301ATD25



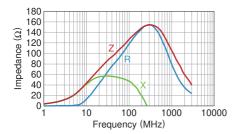
MMZ2012R601ATD25



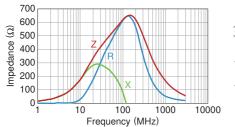
MMZ2012R102ATD25



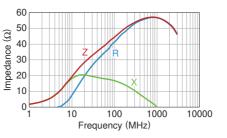
MMZ2012S121ATD25



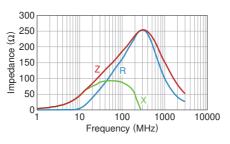
MMZ2012S601ATD25



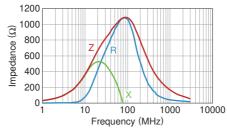
MMZ2012S400ATD25



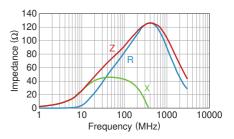
MMZ2012S181ATD25



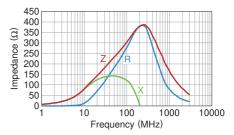
MMZ2012S102ATD25



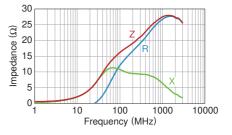
MMZ2012S800ATD25



MMZ2012S301ATD25



MMZ2012Y150BTD25



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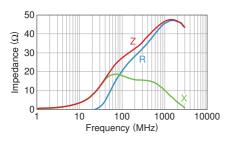
公TDK

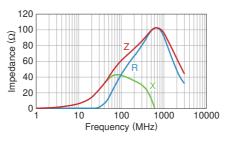
MMZ2012 type

ELECTRICAL CHARACTERISTICS

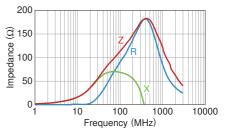
Z, X, R VS. FREQUENCY CHARACTERISTICS

MMZ2012Y300BTD25

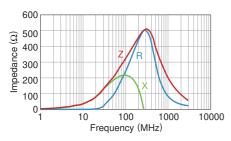




MMZ2012Y121BTD25

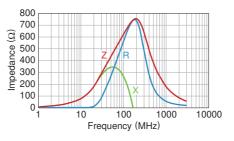


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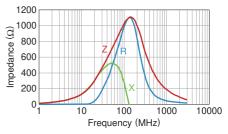


MMZ2012Y601BTD25

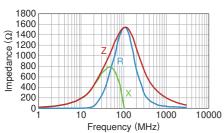
MMZ2012Y600BTD25



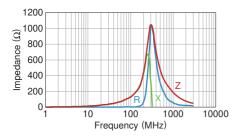
MMZ2012Y102BTD25



MMZ2012Y152BTD25

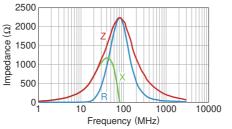


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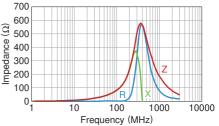


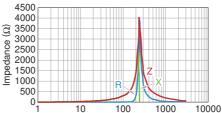
MMZ2012Y202BTD25

MMZ2012D301BTD25



MMZ2012D800BTD25





10

100 1000 Frequency (MHz)

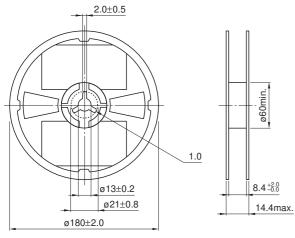
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EMC Components

MMZ2012 type

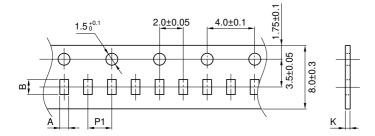
PACKAGING STYLE

REEL DIMENSIONS

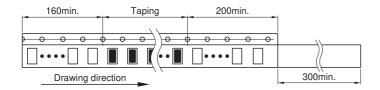


Dimensions in mm

TAPE DIMENSIONS



Dimensions in m				ensions in mm
Туре	А	В	P1	K
MMZ2012	1.5±0.2	2.3±0.2	4.0±0.1	1.1max.



Dimensions in mm